## Advanced Product Information September 2003

## 0.5 to 18 GHz GaAs pHEMT MMIC SPDT Switch

## Features

$\square$ Broadband Coverage: 0.5 to 18.0 GHz
$\square$ Insertion Loss: 1.8 dB Typ. @ 10 GHz
$\square$ Isolation: 35 dB
$\square$ P1dB: +20 dBm, Typical
$\square$ Current Consumption: $50 \mu \mathrm{~A}$, Typ. with Control Voltage of $-7.0 \mathrm{~V}, 0.0 \mathrm{~V}$
$\square 2$ nsec Rise/Fall Time
$\square 0.5 \mu \mathrm{~m}$ pHEMT Technology
$\square$ Small Size: $670 \mu \mathrm{~m} \times 590 \mu \mathrm{~m} \times 76 \mu \mathrm{~m}$ $(\mathbf{2 6 . 4} \mathbf{~ m i l ~ x ~} 23.2 \mathrm{mil} \times 3.0 \mathrm{mil})$

## Applications

- Radar
- Communications
$\square$ Avionics


## - Test and Measurement

## Description

The CSW0118-BD is a single-pole double-throw (SPDT) GaAs pHEMT MMIC switch that covers the frequency range from 0.5 to 18 GHz . The CSW0118-BD is $80 \%$ smaller than comparable broadband FET switch MMICs offering similar performance. It has very low power consumption requirements and offers very fast switching speeds. Celeritek's $0.5 \mu \mathrm{~m}$ pHEMT in-house GaAs process provides for excellent uniformity and high manufacturing yields.

Chip Diagram


DIMENSIONS ARE IN MICRONS.

Backside via holes are used to provide low inductance ground connections and to facilitate ease of use. Goldplated metallization in used on both front side and backside metal. The MMIC is compatible with either eutectic or conductive epoxy die attach and either thermocompression or thermosonic wire bonding. Minimal off-chip components provides ease of use in design and manufacturing steps.

CSW0118-BD SPDT MMIC switches are shipped in Gel Pack from Celeritek's foundry.

Specifications ( $\mathrm{T}_{\mathrm{A}}=\mathbf{2 5}^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=\mathbf{0 . 0 V}$ )

| Parameters | Units | Min | Typ | Max |
| :--- | :---: | :---: | :---: | :---: |
| Frequency Range | GHz | 0.5 |  | 18.0 |
| $\mathrm{Vp}(\mathrm{Vds}=3.0 \mathrm{~V}, \mathrm{Id}=1 \mathrm{~mA})$ | Volts | -1.5 | -1.0 | -0.5 |
| $\mathrm{BVdg0}(100 \mu \mathrm{~A} / \mathrm{mm})$ | Volts | 16.0 | 19.0 |  |
| Idss $(\mathrm{Vds}=3.0 \mathrm{~V})$ | $\mathrm{mA} / \mathrm{mm}$ |  | 150 |  |

RF Specifications at Frequency $\left(\mathrm{T}_{A}=\mathbf{2 5}^{\circ} \mathrm{C}\right)$

| Parameters | $@ \mathbf{0 . 5} \mathbf{G H z}$ | $@ 2.0 \mathrm{GHz}$ | $@ 10.0 \mathrm{GHz}$ | $@ 18.0$ |
| :--- | :---: | :---: | :---: | :---: |
| Insertion Loss, dB | 1.4 | 1.6 | 1.8 | 2.7 |
| Isolation, dB | -40 | -30 | -23 | -24 |
| $\mathrm{P}-1 \mathrm{~dB}, \mathrm{dBm}$ | 20.0 | 21.5 | 21.0 | 21.5 |
| VSWR In/Out | $2.5: 1$ | $1.5: 1$ | $1.5: 1$ | $1.5: 1$ |

## Absolute Maximum Ratings

| Parameter | Rating |
| :--- | :---: |
| Input Power (Pin) | $\geq+30 \mathrm{dBm}$ |
| Control Voltage (Vctrl) | $-10 \mathrm{~V}($ min. $) 0.0 \mathrm{~V}$ (max) |
| Operating Channel Temperature | $+150^{\circ} \mathrm{C}$ |
| Mounting Temperature | $+320^{\circ} \mathrm{C}$ |
| Storage Temperature | $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |

## Biasing and Operation

No voltage is required at the RF input or RF output ports to turn the switch "ON." The control voltage for the desired through path should be set to 0.0 V in order to turn that leg of the switch "ON." The control voltage of the isolated path should be set to a negative voltage exceeding -1.5 V (more negative than -1.5 V ). As the voltage of the isolated path control voltage pad is taken more negative the isolation will improve up to the voltage limit of -7.0 V . See the following Truth Table for an explanation of how to set the through path and the isolated path of the switch.

## Die Attach and Bonding Procedures

Die Attach: Eutectic die attach is recommended. For eutectic die attach: Preform: AuSn ( $80 \% \mathrm{Au}, 20 \% \mathrm{Sn}$ ); Stage Temperature: $290^{\circ} \mathrm{C}, \pm 5^{\circ} \mathrm{C}$; Handling Tool: Tweezers; Time: 1 min or less.
Wire Bonding: Wire Size: 0.7 to 1.0 mil in diameter (prestressed); Thermocompression or thermosonic bonding is acceptable. For thermocompression bonding: Stage Temperature: $250^{\circ} \mathrm{C}$; Bond Tip Temperature: $150^{\circ} \mathrm{C}$; Bonding Tip Pressure: 18 to 40 gms depending on size of wire.

## Truth Table

| Ventrl 1 | Ventrl 2 | Path 1 | Path 2 |
| :--- | :---: | :---: | :---: |
| -2.0 V | 0.0 V | OFF | ON |
| 0.0 V | -2.0 V | ON | OFF |

Schematic Diagram


$\qquad$

## Typical Performance



## Isolation vs Frequency



## Ordering Information

The CSW0118-BD is available in bare die and is shipped in Gel Pak.

Part Number for Ordering

## CSW0118-BD

Description

## Bare Die

Celeritek reserves the right to make changes without further notice to any products herein. Celeritek makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Celeritek assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Celeritek does not convey any license under its patent rights nor the rights of others. Celeritek products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Celeritek product could create a situation where personal injury or death may occur. Should Buyer purchase or use Celeritek products for any such unintended or unauthorized application, Buyer shall indemnify and hold Celeritek and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Celeritek was negligent regarding the design or manufacture of the part. Celeritek is a registered trademark of Celeritek, Inc. Celeritek, Inc. is an Equal Opportunity/Affirmative Action Employer.

